

C1808C330JHGACTU

Aliases (C1808C330JHGAC7800) SMD Comm COG HV, Ceramic, 33 pF, 5%, 3,000 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 1808, 2.9 mm



General Information	
Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	81 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1808
L	4.7mm +/-0.5mm
W	2mm +/-0.2mm
Т	1.6mm +/-0.15mm
S	2.9mm MIN
В	0.6mm +/-0.35mm

W	2mm +/-0.2mm	Tolerance	5%
Т	1.6mm +/-0.15mm	Voltage DC	3000 VDC
S	2.9mm MIN	Dielectric Withstanding Voltage	3,600 VDC
В	0.6mm +/-0.35mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Capacitance Change with	30 ppm/C, 1MegaHz 1.0Vrms
Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	,,,,,
Packaging Quantity 1000	Dissipation Factor	0.1% 1 MHz 1.0Vrms	
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Specifications	
Capacitance	33 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	5%
Voltage DC	3000 VDC
Dielectric Withstanding Voltage	3,600 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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